## **UNHZ202**

## Circuit Protector Elements

## For overcurrent protection

#### ■ Features

- Sharp cutoff characteristics and low voltage drop
- Flame retardant package and low heat generation, high density mounting is possible.

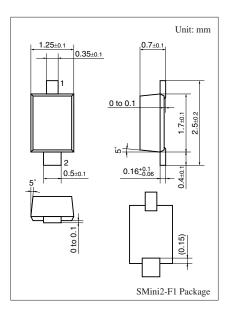
## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Operating ambient temperature	$T_{opr}$	-55 to +125	°C	
Storage temperature	$T_{stg}$	-55 to +125	°C	

## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

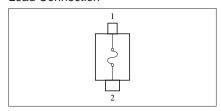
Parameter	Min	Тур	Max	Unit
Rated voltage		50		V
Rated current		1.0		A
Internal Resistance	45	59	73	mΩ
Cutoff current *		2.0		A

Note) \*: Measurement condition of cutoff current shall be at  $T_a$  = 25°C, t = 1 s Tolerance of cutoff current shall be  $\pm$  20%



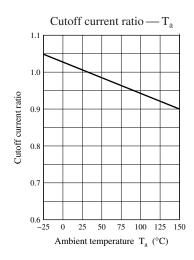
Marking Symbol: H2

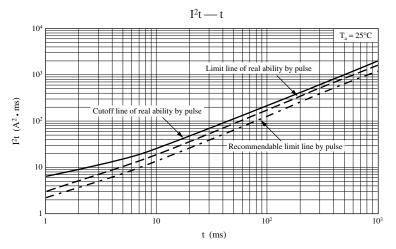
#### Lead Connection



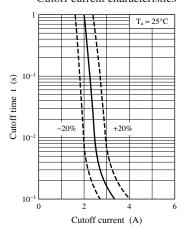
#### ■ Usage Notes

- Package shall be overheated and dangerous for overcurrent.
- This device should be used only to the secondary circuit. Package will be damaged for added overpower.
- This device is not electrical fuse legally. Please draw a clear line between electrical fuse from this device.





### Cutoff current characteristics



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